

SPECIFICATION FOR SMT VCXO MtronPTI M3006S081

I. GENERAL & ELECTRICAL REQUIREMENTS:

1. FREQUENCY OF OPERATION: 19.440000 MHz
2. OPERATING TEMPERATURE RANGE: -40°C to +85°C
3. OPERATING VOLTAGE: 3.3 V $\pm$ 10%
4. OPERATING CURRENT: 40 mA max.
5. OUTPUT TYPE: HCMOS Compatible
6. SYMMETRY: 45/55% ref. to $\frac{1}{2}$ Vdd
7. RISE/FALL TIME: 5 nS max. ref. 10% to 90% Vdd
8. OUTPUT LOGIC LEVELS: V_{OL} = 10% Vdd max. V_{OH} = 90% Vdd min.
9. OUTPUT LOAD: 15 pF max.
10. PULLABILITY (APR): $\pm$ 50 ppm min. (Includes initial tolerance, deviation over temperature, aging, load & supply variations, shock and vibration effects).
11. LINEARITY: 10% max. with positive monotonic slope.
12. CONTROL VOLTAGE (Pin 1): 0.3 V to 3.3 V (1.65 V for center frequency)
13. MODULATION BANDWIDTH (-3 dB): 10 kHz min.
14. INPUT IMPEDANCE (Pin 1): 50 K min. at 10 kHz
15. TRISTATE FUNCTION (Pin 5): Logic level "1" or floating enables output. Logic level "0" disables output to Hi-Z.
16. PHASE NOISE (SSB Typical): -70 dBc/Hz @ 10 Hz, -100 dBc/Hz @ 100Hz, -129dBc @ 1kHz, -145 dBc/Hz @ 10 kHz, -152 dBc/Hz @ 100kHz.

II. ENVIRONMENTAL & MECHANICAL REQUIREMENTS:

1. SHOCK: MIL-STD-202, Method 213, Condition C.
2. VIBRATION: MIL-STD-202, Methods 201 & 204.
3. HERMETICITY: 1 X 10⁻⁸ atm cc/sec min.
4. STORAGE TEMPERATURE: -55°C to +125°C
5. SOLDERABILITY: Per EIAJ-STD-002
6. MAXIMUM SOLDERING CONDITIONS: See Figure 1
7. PACKAGE: 6-pad leadless ceramic package. RoHS compliant.

III. DIMENSIONS:

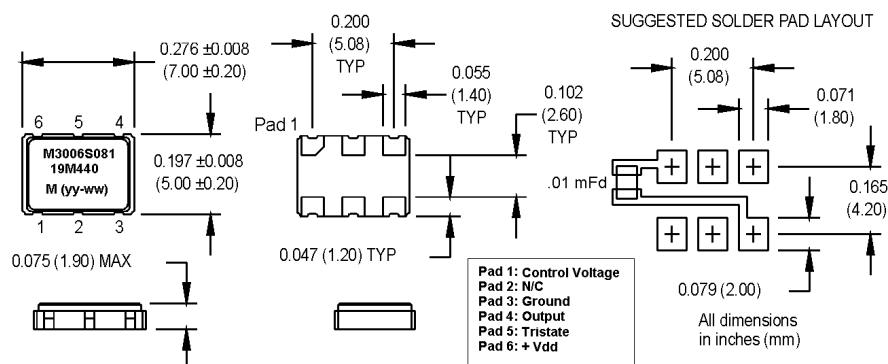
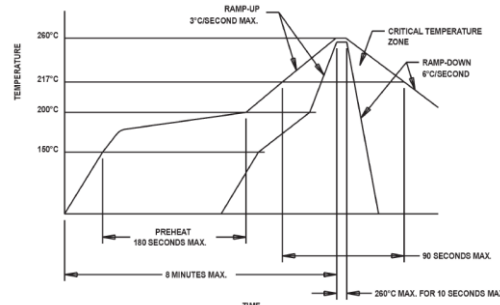


Figure 1



IV. DATA SHEET REVISION TABLE:

Date	Rev.	Author	Details of Revision
2/8/05	0	WNJ	Original release.